**ORDER DESCRIPTION**

1. **Object of the contract**

The subject of the order is the supply of semiconductors wafers listed below by name and quantity needed:

* GaAs 2” 60 psc.
1. **The scope of the subject of the contract**

A detailed description of the subject of the contract is provided in section 5 of this document.

1. **Criterion**

Offers will be evaluated according to a point scale with a maximum number of points of 100.

|  |  |  |
| --- | --- | --- |
| Criterion | Maximum number of points S | Method of awarding points |
| Net Price (P) | 100 | S x Pmin/Pi |

Where:

* Pi – net price of goods - for the given offer
* Pmin - the minimum net price for the ordered goods from all offers submitted
* S – number of points

The final score will be calculated by adding up the partial components and then rounded to two decimal places (rounded from "5" up).

1. **Deadline for completing the order**

**8 weeks from the date of placing the order.**

1. **Parameters**

**5.1 Detailed scope of the subject**

|  |  |  |  |
| --- | --- | --- | --- |
| Product name |  | Parametrer | Specification |
| **GaAs**  | Diameter 2” Thickness: 1.1. mm | Grade: | Epi-ready grade |
| Growth method | VGF |
| Conduct type | Semi-insulating (S-I) |
| Dopant | undoped |
| Orientation: | (100)±0.2o |
| Primary Flat: | EJ (0-1-1) |
| Secondary Flat | EJ (0-11)  |
| Resistivity: | min 1E8 Ω/cm |
| EPD (Average):: | <5000/cm2 max |
| Mobility: | Min: 4870 Max: 6050 cm^2/V\*cm |
| Surface Finish: | Surface side 1 Epi-ready gradeSurface side 2 polish |
| Packaging: | ePAK |